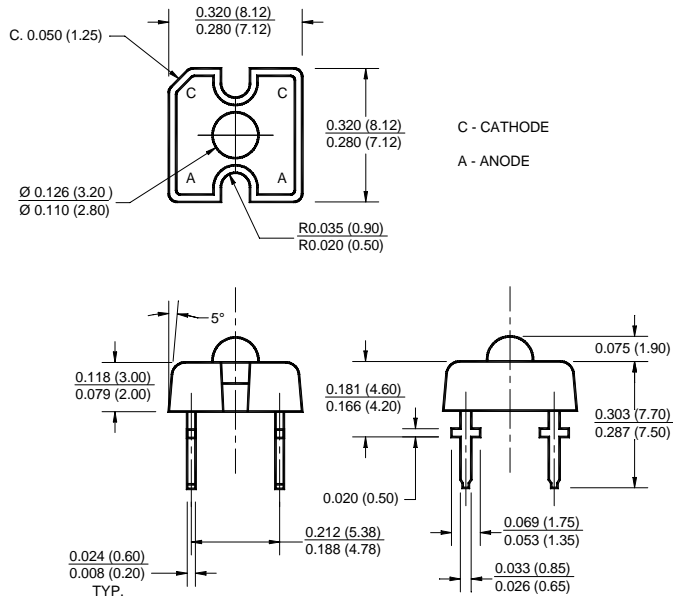


## PACKAGE DIMENSIONS



### NOTES:

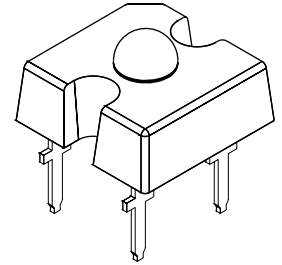
1. Dimensions for all drawings are in inches (mm).
2. Lead spacing is measured where the leads emerge from the package.
3. Protruded resin under the flange is 0.059" (1.5 mm) max.
4. All tolerances are  $\pm 0.10$ " (0.25 mm) unless otherwise specified.

**WHITE**

**QTLP321C-W**

## FEATURES

- InGaN (Indium Gallium Nitride) technology
- Fluorescent light emission
- Reduced thermal resistance
- Tube packaging



## DESCRIPTION

This low profile, 4-pin LED provides a more uniform and evenly distributed illumination than existing LED designs. Its unique optical package enables designers to utilize fewer LEDs while achieving superior lighting performance.

## APPLICATIONS

- Exterior automotive lighting
- Area displays
- Backlighting
- Message panels

## ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Operating Temperature	$T_{OPR}$	-25 to +80	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-30 to +100	$^\circ\text{C}$
Lead Soldering Time	$T_{SOL}$	260 for 5 sec	$^\circ\text{C}$
Continuous Forward Current	$I_F$	20	mA
Peak Forward Current ( $f = 100$ Hz, Duty Factor = 1/10)	$I_F$	100	mA
Reverse Voltage	$V_R$	5	V
Power Dissipation	$P_D$	120	mW

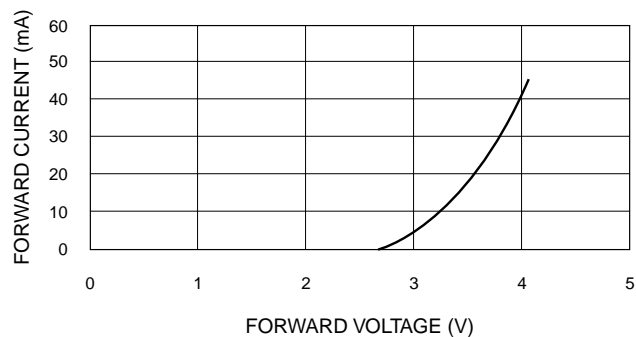
**WHITE**

**QTLP321C-W**

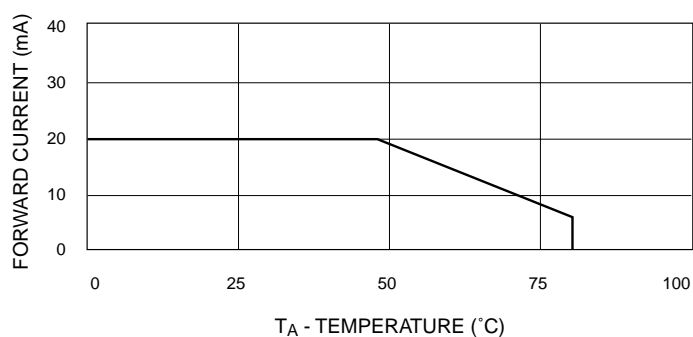
## ELECTRICAL / OPTICAL CHARACTERISTICS (T<sub>A</sub> = 25°C)

Part Number	QTLP321C-W	Condition
Flux - $\Phi_V$ (lm)		I <sub>F</sub> = 20 mA
Minimum	250	
Typical	500	
Chromatic Coordinates - Typical	X = 0.32, Y = 0.32	I <sub>F</sub> = 20 mA
Peak Wavelength (nm)	550	I <sub>F</sub> = 20 mA
Forward Voltage V <sub>F</sub> (V):		I <sub>F</sub> = 20 mA
Typical	3.5	
Maximum	4.0	
Viewing Angle (°)	50	I <sub>F</sub> = 20 mA

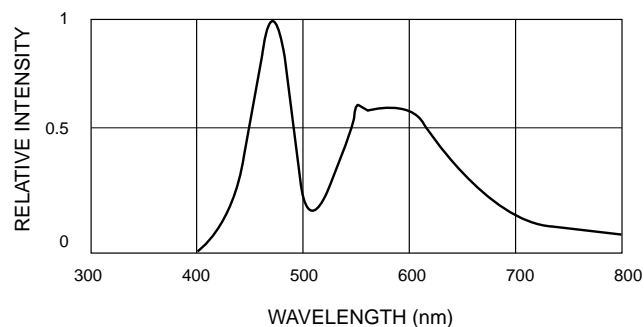
## TYPICAL PERFORMANCE CURVES



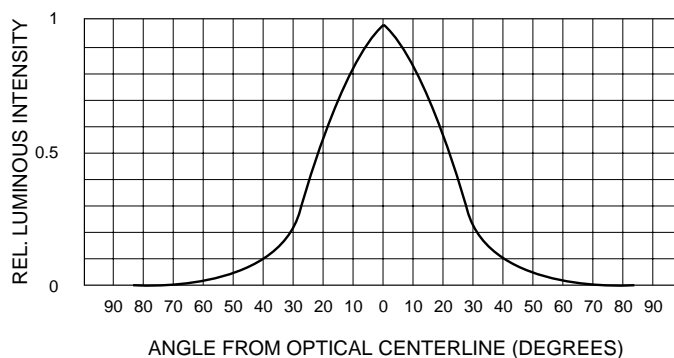
**Fig. 1 Forward Voltage vs. Forward Current**



**Fig. 2 Forward Current vs. Ambient Temperature**



**Fig. 3 Relative Intensity vs. Wavelength**



**Fig. 4 Rel. Luminous Intensity vs. Angular Displacement**

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2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.